

L Number	Hits	Search Text	DB	Time stamp
-	589	((flat near package) and (leadframe (lead adj frame)))	USPAT; EPO; JPO	2003/03/23 09:13
-	201	((flat near package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2001/05/20 11:05
-	500	((flat near package) and (leadframe (lead adj frame))) and (wire wiring)	USPAT; EPO; JPO	2001/05/16 14:08
-	318	((flat near package) and (leadframe (lead adj frame))) and (wire wiring) not (((flat near package) and (leadframe (lead adj frame))) and opening)	USPAT; EPO; JPO	2001/05/20 11:07
-	5	(leadframe (lead adj frame)) near4 ((cupric adj oxide) (anodic adj oxidation) (chemical adj oxidation))	USPAT; EPO; JPO	2001/05/18 08:19
-	201	((flat nearl package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2001/05/20 11:09
-	182	((flat nearl package) and (leadframe (lead adj frame))) and opening) and (wire wiring)	USPAT; EPO; JPO	2003/03/22 12:51
-	500	(flat nearl package) and (leadframe (lead adj frame)) and (wire wiring)	USPAT; EPO; JPO	2001/09/07 08:05
-	231	((flat nearl package) and (leadframe (lead adj frame)) and (wire wiring)) and (plated plating)	USPAT; EPO; JPO	2001/05/20 11:12
-	522	(flat nearl package) and (leadframe (lead adj frame)) and (wire wiring)	USPAT; EPO; JPO	2002/01/28 15:59
-	94	((flat nearl package) and (leadframe (lead adj frame)) and (wire wiring)) and ring	USPAT; EPO; JPO	2001/09/07 08:23
-	3	((flat nearl package) and (leadframe (lead adj frame)) and (wire wiring)) and ((power ground grounding) nearl ring)	USPAT; US-PCPUB; EPO; JPO;	2001/09/07 08:25
-	0	(leadframe (lead adj frame)) with (tross adj reducing) with (power ground grounding) and (wire wiring)	USPAT; EPO; JPO	2001/09/07 08:50
-	5	"5776800"	USPAT; EPO; JPO	2001/09/07 08:50
-	556	(flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)	USPAT; EPO; JPO	2002/01/28 16:00
-	381	((flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)	USPAT; EPO; JPO	2002/01/28 16:02
-	378	((flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die ic (integrated adj circuit)) (semiconductor nearl (device package)))	USPAT; EPO; JPO	2002/01/28 16:04
-	377	((flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)) (semiconductor nearl (device package)))	USPAT; EPO; JPO	2002/01/28 16:16
-	364	((flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)) (semiconductor nearl (device package))) and surface	USPAT; EPO; JPO	2002/01/28 16:16
-	115	((flat nearl packag\$3) and (leadframe (lead adj frame)) and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)) (semiconductor nearl (device package))) and surface) and ((die adj pad) (mount\$3 adj (area pad)))	USPAT; EPO; JPO	2002/01/28 16:18

191	(((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package)))) and surface) and (lead with (stepped step recess protrusion))	USPAT; EPO; JPO	2002/01/28 16:20
64	(((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package)))) and surface) and ((die adj pad) (mount\$3 adj (area pad)))) and (lead with (stepped step recess protrusion))	USPAT; EPO; JPO	2002/01/28 16:20
12	AZUMA-KOSUKE AZUMA-KOUSUKE	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:51
0	20010009301.URPN.	USPAT	2002/03/27 08:51
9	"6071755"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
3	"6247229"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
2	"6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
14	"6071755" "6247229" "6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
3	"6084310"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
3	"6163069"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
6	"6198171"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
4	"6238952"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
4	"6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
19	"6084310" "6163069" "6198171" "6238952" "6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
7	("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:54
33	"6071755" "6247229" "6208021" ("6084310" "6163069" "6198171" "6238952" "6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:18

21	{("6071755" "6247229" "6208021")} {"6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 09:42
1	6215179.URPN.	USPAT	2002/03/27 09:00
2	{("6031292" "6215179").PN.	USPAT	2002/03/27 09:01
3	6031292.URPN.	USPAT	2002/03/27 09:01
2	{("5371407" "5625222").PN.	USPAT	2002/03/27 09:02
0	6348726.URPN.	USPAT	2002/03/27 09:02
0	6208021.URPN.	USPAT	2002/03/27 09:03
9	{("4849857" "4908736" "5444301" "5583375" "5767571" "5770888" "5801439" "5821615" "5849608").PN.	USPAT	2002/03/27 09:03
3	{("4604644" "4974057" "5283446").PN.	USPAT	2002/03/27 09:04
10	5444301.URPN.	USPAT	2002/03/27 09:05
3	{("5863805" "5886405" "5917241").PN.	USPAT	2002/03/27 09:10
1	6084310.URPN.	USPAT	2002/03/27 09:10
7	6071755.URPN.	USPAT	2002/03/27 09:11
10	{("5285352" "5313365" "5355283" "5371404" "5394009" "5450283" "5461197" "5554887" "5578525" "5619070").PN.	USPAT	2002/03/27 09:12
71	5450283.URPN.	USPAT	2002/03/27 09:14
4	6081997.URPN.	USPAT	2002/03/27 09:19
9	{("4143456" "4766095" "5134773" "5218759" "5420752" "5450283" "5474958" "5962296" "5732463").PN.	USPAT	2002/03/27 09:20
71	5450283.URPN.	USPAT	2002/03/27 09:21
11	{("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN.	USPAT	2002/03/27 09:21
5	5981312.URPN.	USPAT	2002/03/27 09:25
5	5981312.URPN.	USPAT	2002/03/27 09:25
18	{("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.	USPAT	2002/03/27 09:25
13	5817545.URPN.	USPAT	2002/03/27 09:28
12	{("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.	USPAT	2002/03/27 09:30
12	{("6071755" "6247229" "6208021")} {"6084310" "6163069" "6198171" "6238952" "6215179") not ({("6071755" "6247229" "6208021") {"6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball))}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:15
5	{("5900676" "6187614" "6198171" "6201292" "6208023").PN.	USPAT	2002/03/27 09:45
10	{("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.	USPAT	2002/03/27 09:49
7	5373190.URPN.	USPAT	2002/03/27 09:50
5	{("3922712" "3959874" "3972062" "4839713" "5019673").PN.	USPAT	2002/03/27 09:53
84	3781596.URPN.	USPAT	2002/03/27 09:54
84	3781596.URPN.	USPAT	2002/03/27 09:54
12	5900676.URPN.	USPAT	2002/03/27 09:57
1	6069408.URPN.	USPAT	2002/03/27 10:02
7	{("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.	USPAT	2002/03/27 10:02
13	5656550.URPN.	USPAT	2002/03/27 10:04
5	5830800.URPN.	USPAT	2002/03/27 10:07
3	{("5830800" "6077766" "6232661").PN.	USPAT	2002/03/27 10:09
2	{("5620928" "5656550").PN.	USPAT	2002/03/27 10:09
5	5847458.URPN.	USPAT	2002/03/27 10:10

-	5	5817458.URPN.	USPAT	2002/03/27	10:10
-	5	("4697943" "5463593" "5471088"	USPAT	2002/03/27	10:11
-	402288	"5497032" "5656550").PN. semiconductor near1 (device package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27	10:17
-	33	(semiconductor near1 (device package packaging)) and (lead adj (pot post))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27	10:22
-	494	(semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27	10:25
-	216	((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27	10:28
-	263	((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. (("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. (("5082615" "5203076" "5218234" "5248710" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) ((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (("6071755" "6247229" "6208021") (("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. (("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27	10:30

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211 (((semiconductor nearl (device package
packaging)) and ((leadframe (lead adj
frame)) with (chip die) with (bump ball)))
and ((sealing adj (rosin material))
encapsulant encapsulating encapsulated))
not (((("6071755" "6247229" "6208021")
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95 (((semiconductor nearl (device package
packaging)) and ((leadframe (lead adj
frame)) with (chip die) with (bump ball)))
and ((sealing adj (resin material))
encapsulant encapsulating encapsulated))
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"5900676" | "5930603").PN.) 5656550.URPN.))
and (conductive adj (adhesive material
epoxy))

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USPAT; 2002/03/27 10:31
US-PGPUB;
EPO; JPO;
DERWENT

USPAT; 2002/03/27 10:43
US-PGPUB;
EPO; JPO;
DERWENT

I16 (((semiconductor near1 (device package
 packaging)) and ((leadframe (lead adj
 frame)) with (chip die) with (bump ball)))
 and ((scaling adj (resin material))
 encapsulant encapsulating encapsulated))
 not (((("6071755" "6247229" "6208021")
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 (((("6084310" "6163069" "6198171" "6238952"
 "6215179" and (bump ball)))) ((("3781596" |
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 adj frame)) with (chip die) with (bump
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 "5900676" | "5930603").PN.) 5656550.URPN.))
 and (conductive adj (adhesive material
 epoxy)))
 535 "116" and (lead near2 exposed)

USPAT;
 US-PGPUB;
 EPO; JPO;
 DERWENT

2002/03/27 10:44

USPAT;
 US-PGPUB;
 EPO; JPO;
 DERWENT

2002/03/27 10:45

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16 ((((((semiconductor near1 (device package
package packaging)) and ((leadframe (load adj
frame)) with (chip die) with (bump ball)))
and ((sealing adj (resin material))
encapsulant encapsulating encapsulated))
not (((("6071755" "6247229" "6208021")
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((("6084310" "6163069" "6198171" "6238952"
"6215179") and (bump ball)))) ((("3781596" |
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ball))) and ((sealing adj (resin material))
encapsulant encapsulating encapsulated))
not (((("6071755" "6247229" "6208021")
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and (conductive adj (adhesive material
epoxy)))) and (lead near2 exposed)

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USPAT:
US-PCPUB;
EPO: JPO;
DERWENT

2002/03/27 10:46

100	<pre> ((((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. (((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. (((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (("6071755" "6247229" "6208021") (("6084310" "6163069" "6198171" "6238952" "6215179" and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. (((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) not (((((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. (((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. (((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (("6071755" "6247229" "6208021") (("6084310" "6163069" "6198171" "6238952" "6215179" and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. (((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) and (conductive adj (adhesive material epoxy))) not (((((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. (((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. </pre>	USPAT; US-PGPUB; KPO; JPO; DERWENT	2002/03/27 10:47
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5	("5285104" "5663593" "6002173"	USPAT	2002/03/27 10:51
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8	((flat near1 package) and (leadframe (lead adj frame))) and ((test testing) with (singulation singulating singulated cutting saw))	USPAT; EPO; JPO	2002/03/28 06:55
1	"6343019"	USPAT; EPO; JPO	2002/03/28 06:59
3	"6157080"	USPAT; EPO; JPO	2002/03/28 06:59
1	"6258626"	USPAT; EPO; JPO	2002/03/28 07:02
4	"6157080" "6258626"	USPAT; EPO; JPO	2002/03/28 07:02
3434	substrate near3 thickness near3 mm	USPAT; EPO; JPO	2002/03/28 14:56
58	(substrate near3 thickness near3 mm) and (flipchip (flip adj chip))	USPAT; EPO; JPO	2002/03/28 14:56
1	"6329705"	USPAT; EPO; JPO	2002/04/16 06:35
25	"5570272"	USPAT; EPO; JPO	2002/04/16 06:35
8	"5750423"	USPAT; EPO; JPO	2002/04/16 06:36
4	"6013947"	USPAT; EPO; JPO	2002/04/16 06:37
37	"6329705" "5570272" "5750423" "6013947"	USPAT; EPO; JPO	2002/04/16 06:37
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1	"5757066").PN.	USPAT	2002/04/16 06:40
3	6028368.URPN.	USPAT	2002/04/16 06:40
38	5223739.URPN.	USPAT	2002/04/16 06:46
3	6028368.URPN.	USPAT	2002/04/16 06:49
881	(flat near package) and (leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/31 16:00
286	((flat near package) and (leadframe (lead adj frame))) and (flipchip (flip adj chip) bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:02
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79	(((flat near package) and (leadframe (lead adj frame))) and (flipchip (flip adj chip bump ball)) not ("6329705" "5570272" "5750423" "6013947") not (("4523218" "4987473" "4994895" "5197183" "5223739" "5252783" "5291059" "5291061" "5345106" "5357674" "5369058" "5530281" "5543658" "5570272" "5581121" "5594234" "5644161" "5692296" "5736432" "5783861" "5866939" "5905301" "5910681" "5932923" "6028368").PN.)) and plastic and tab	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:19
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46	"5172214"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:37
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6	"5969416"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:40
2	"6124546"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:41
3	"6084310"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 07:45
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3	("5863805" "5886405" "5917241").PN.	USPAT	2002/04/16 07:47
6	("3200364" "4897708" "4987100" "5034349" "5172214" "5206188").PN.	USPAT	2002/04/16 07:49
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7	6043430.URPN.	USPAT	2002/04/16 07:54
6	("5363279" "5583375" "5744827" "5770888" "5801439" "5804874").PN.	USPAT	2002/04/16 07:55
15	5436500.URPN.	USPAT	2002/04/16 08:00
14	5594234.URPN.	USPAT	2002/04/16 08:02
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1	6124546.pn.and "40"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 08:29
2	6124546.pn.and "16"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/16 08:30